

Amendments to the Claims

1. *(Currently Amended)* A wafer ~~(1)~~, which wafer ~~(1)~~ comprises a number of exposure fields ~~(2)~~ and which wafer ~~(1)~~ comprises a number of intersecting, lattice-like dicing path sections ~~(6A, 6B, 6C, 8A, 8B, 8C, 8D)~~ and a number of lattice fields ~~(3)~~ in each exposure field ~~(2)~~, wherein each lattice field ~~(3)~~ contains an IC ~~(4)~~, and which wafer ~~(1)~~ comprises a first group ~~(5)~~ of first dicing paths ~~(6)~~ and a second group ~~(7)~~ of second dicing paths ~~(8)~~, wherein all of the first dicing paths ~~(6)~~ of the first group ~~(5)~~ run parallel to a first direction ~~(X)~~ and have a first path width ~~(W1)~~ and wherein all of the second dicing paths ~~(8)~~ of the second group ~~(7)~~ run parallel to a second direction ~~(Y)~~ intersecting the first direction ~~(X)~~ and have a second path width ~~(W2)~~, and wherein the first dicing paths ~~(6)~~ consist of a plurality of first dicing path sections ~~(6A, 6B, 6C)~~ arranged consecutive to one another in the first direction ~~(X)~~ and the second dicing paths ~~(8)~~ consist of a plurality of second dicing path sections ~~(8A, 8B, 8C, 8D)~~ arranged consecutive to one another in the second direction ~~(Y)~~, and wherein the first dicing paths ~~(6)~~ and the second dicing paths ~~(8)~~ are provided and designed for a subsequent segregation of the lattice fields ~~(3)~~ and the ICs ~~(4)~~ contained therein, and wherein each exposure field ~~(2)~~ has a first edge ~~(R1, S1, T1)~~ extending parallel to the first direction ~~(X)~~ and a second edge ~~(R2, S2, T1)~~ extending parallel to the first direction ~~(X)~~ and lying opposite the first edge ~~(R1, S1, T1)~~, and wherein at least two control module fields ~~(A1, A2, B1, B2, C1, D1, D2, E1, E2, F1)~~ are assigned to each exposure field ~~(2)~~, each of which control module fields contains at least one optical control module ~~(OCM-A1, OCM-A2, OCM-B1, OCM-B2, OCM-C1, OCM-D1, OCM-D2, OCM-E1, OCM-E2, OCM-F1)~~, and wherein a first control module field ~~(OCM-A1, OCM-B1, OCM-C1, OCM-D1, OCM-E1, OCM-F1)~~ of each exposure field ~~(2)~~ immediately adjoins the first edge ~~(R1, S1, T1)~~ of the exposure field ~~(2)~~ in question and lies between the first edge ~~(R1, S1, T1)~~ and a row of lattice fields ~~(3)~~ extending parallel to the first direction ~~(X)~~ in a first dicing path section ~~(6A, 6B, 6C)~~ and thus in a first dicing path ~~(6)~~, and wherein a second control module field ~~(OCM-A2, OCM-B2, OCM-D2, OCM-E2)~~ of each exposure field ~~(2)~~ lies at a preset distance from the second edge ~~(R2, S2)~~ between two rows of lattice fields ~~(3)~~ extending parallel to the first direction ~~(X)~~ and arranged adjacent to one another, and thus likewise in a first dicing path ~~(6)~~.

2. *(Currently Amended)* A wafer ~~(1)~~ as claimed in claim 1, wherein the second control module field ~~(OCM A2, OCM B2, OCM D2, OCM E2)~~ of each exposure field ~~(2)~~ immediately adjoins the row of lattice fields ~~(3)~~, which row of lattice fields ~~(3)~~ immediately adjoins the second edge ~~(R2, S2)~~ of the exposure field in question ~~(2)~~.